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PMP8866 Rev B Bill of Materials

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
!PCB	1		Printed Circuit Board		PMP8866	Any
C1	1	1000pF	CAP, CERM, 1000pF, 3kV, 1808	1808	STD	STD
C2	1	100uF	CAP, AL, 100uF, 50V, +/-20%, 0.34 ohm, SMD	SMT Radial F	EEE-FK1H101P	Panasonic
C3, C4, C5, C6, C7, C24	6	4.7uF	CAP, CERM, 4.7uF, 50V, +/-10%, X7R, 1206	1206	GRM31CR71H475KA12L	MuRata
C8	1	0.1uF	CAP, CERM, 100V, +/-10%, X7R, 0805	0805	STD	STD
C9	1	470uF	CAP, AL, 470uF, 10V, +/-20%, 0.16 ohm, SMD	SMT Radial F	EEE-FK1A471P	Panasonic
C10, C11	2	47uF	CAP, CERM, 16V, +/-10%, X7R, 1210	1210	STD	STD
C12, C13, C17	3	0.1uF	CAP, CERM, 25V, +/-10%, X7R, 0402	0402	STD	STD
C14	1	0.01uF	CAP, CERM, 100V, +/-10%, X7R, 0603	0603	STD	STD
C15	1	100uF	CAP, AL, 100uF, 25V, +/-20%, 30 ohm, SMD	6.3x7.7	EEHZA1E101XP	Panasonic
C16	1	1000pF	CAP, CERM, 25V, +/-10%, X7R, 0402	0402	STD	STD
C18	1	0.047uF	CAP, CERM, 25V, +/-10%, X7R, 0402	0402	STD	STD
C19	1	47pF	CAP, CERM, 50V, +/-10%, X7R, 0402	0402	STD	STD
C20	1	1uF	CAP, CERM, 16V, +/-10%, X5R, 0402	0402	STD	STD
C21	1	3300pF	CAP, CERM, 50V, +/-10%, X7R, 0402	0402	STD	STD
C22	1	10uF	CAP, CERM, 16V, +/-10%, X5R, 1206	1206	STD	STD
C23	1	100pF	CAP, CERM, 50V, +/-10%, X7R, 0402	0402	STD	STD
D1, D7	2	0V	Diode, Switching, 70V, 0.25A, SOT-23	SOT-23	BAW56-V-GS08	Vishay-Semiconductor
D2, D3, D4, D5, D6, D8, D9	7	1.4V	Diode, Ultrafast, 100V, 0.25A, SOD-323	SOD-323	BAS316,115	NXP Semiconductor
D11, D100	2	0.0875V	Diode, Ultrafast, 200V, 1A, SMA	SMA	MURA120T3G	ON Semiconductor
J1, J2	2		TERMINAL BLOCK 5.08MM VERT 2POS	TERM_BLK, 2pos, 5.08mm	ED120/2DS	On-Shore Technology, Inc.
L1	1	6 uH	Inductor, SMT, y14.4A, 4.4milliohm	0.750 x 0.875 inch	PA2729.602NL	Pulse
L2	1	1mH	Inductor, Shielded Drum Core, Ferrite, 1mH, 0.11A, 16.3 ohm, SMD	LPS4414	LPS4414-105MLB	Coilcraft
L3	1	4.7uH	INDUCTOR POWER 4.7UH 8.2A SMD	12.5 x 12.5mm	SRR1280-4R7Y	Bourns
Q1, Q3	2	60V	MOSFET, N-CH, 60V, 172A, SON 5x6mm	SON 5x6mm	CSD18532Q5B	Texas Instruments
Q2, Q8, Q12	3	0.2V	Transistor, NPN, 40V, 0.2A, SOT-23	SOT-23	MMBT3904	Fairchild Semiconductor
Q4, Q11, Q13	3	0.25V	Transistor, PNP, 40V, 0.2A, SOT-23	SOT-23	MMBT3906	Fairchild Semiconductor
Q5, Q7	2	25V	MOSFET N CH 100V 24A 8-SOP	SON 5x6mm	TPH1400ANH,L1Q	Toshiba
Q6	1	-30V	MOSFET P-CH 150V 2.2A 8-SOIC	SOIC-8	IRF6216TRPBF	International Rectifier
R1, R3	2	1k	RES, 1%, 0.25W, 1206	1206	STD	STD
R2, R4, R9, R18, R21, R28	6	10k	RES, 1%, 0.063W, 0402	0402	STD	STD
R5	1	0.51	RES, 1%, 1W, 2512	2512	STD	STD
R6, R8	2	75k	RES, 1%, 0.063W, 0402	0402	STD	STD
R7	1	40.2k	RES, 1%, 0.063W, 0402	0402	STD	STD
R10, R11	2	3.01k	RES, 1%, 0.063W, 0402	0402	STD	STD
R12	1	100k	RES, 1%, 0.063W, 0402	0402	STD	STD
R13	1	86.6k	RES, 1%, 0.063W, 0402	0402	STD	STD
R14, R17	2	0	RES, 1%, 0.063W, 0402	0402	STD	STD
R15, R27	2	0.04	RES, 1%, 1W, 2512	2512	STD	STD
R16, R19, R24, R25	4	1k	RES, 1%, 0.063W, 0402	0402	STD	STD
R20	1	15k	RES, 1%, 0.063W, 0402	0402	STD	STD
R22	1	2.61k	RES, 1%, 0.063W, 0402	0402	STD	STD
R23	1	2k	RES, 1%, 0.1W, 0603	0603	STD	STD
R26	1	7.5k	RES, 1%, 1W, 2512	2512	STD	STD
T1	1	50 Uh	Transformer, Forward 120W, SMT	XFMR, 1240x650x1449 mil	G135038LF	GCI Technologies
TP1, TP3, TP5, TP6	4	Red	Test Point, TH, Miniature, Red	Keystone5000	5000	Keystone
TP2, TP4	2	Black	Test Point, TH, Miniature, Black	Keystone5001	5001	Keystone
U1	1		Advanced Active Clamp PWM Controller with Current Control, -40 to +125 degC, 20-pin QFN (RGP), Green (RoHS & no Sb/Br)	RGP0020D	UCC2897ARGPR	Texas Instruments
U2	1		OPTOCOUPLR PHOTOTRANS 125% 4LSOP	8x2x4mm	VOL618A-2T	Vishay-Semiconductor
U3	1		PRECISION PROGRAMMABLE REFERENCE, DBZ0003A	DBZ0003A	TL431AIDBZ	Texas Instruments

Notes:

Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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